

ABSTRACT OF THE DISCLOSURE

Disclosed are a multi-layer printed circuit board and  
a method for manufacturing the multi-layer printed circuit  
5      board. Circuit layers and insulating layers are alternately  
stacked so that via holes of the circuit layers provided  
with plated inner walls without application of additional  
plating and conductive paste-filling steps are connected to  
via holes of the insulating layers filled with a conductive  
10     paste.